IPC - ASSOCIATION CONNECT ELECTRONICS INDUSTI	© Copyright 2005. IPC	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			er both This clevel	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					als and Mf	g Informati	ion		
upplier Infor	mation								,						
Company name*			Company unique ID			Unio	Unique ID Authority					Response Date*			
nsemi											2024-04-20				
Contact Name		Tit	Title - Contact			Pho	Phone - Contact*				Email - Contact*				
Product-Env-Ste	wards	Pro	Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Repre	esentative*	Tit	Title - Representative			Pho	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reque	ster Item Number	NCP170AXV300T2G Ultra-Low IQ 150		Mfr Item Name		Eff	fective Date	Version	Mai	Manufacturing Site		eight*	UOM	Unit Type	
				Ultra-Low IQ 150 m Regulator, Act Discl			24-04-20	MY1			2.	79	mg	Each	
Ianufacturin	g Proccess Information	on													
Terminal Plating / Grid Array Material Terminal Base Al			lloy J-S	ΓD-020 MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cycles						eles					
Matte Tin (Sn) - annealed			CU Alloy 1				260	C 30		second	s 3				
omments	·	•		·	·					_			•		
vel 1 - maximun	n time at peak temperature	e during solderi	ing is 10-30	seconds					·						
or more informa	ntion regarding material co	omposition plea	se refer to	page 3	-	•					•		_	_	

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correct one bents it is form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.12	mg	Supplier	Silicon (Si)	7440-21-3		0.12	mg
Lead Frame	1.18		В	Nickel (Ni)	7440-02-0		0.4283	mg
			Supplier	Iron (Fe)	7439-89-6		0.5924	mg
			Supplier	Copper (Cu)	7440-50-8		0.1593	mg
Mold Compound-Black	1.4		Supplier	Boron zinc hydroxide oxide	138265-88-0		0.042	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		0.007	mg
			Supplier	2,4,6-triamino-s-triazincompd.withs-triazine-triol	37640-57-6		0.042	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		1.12	mg
			Supplier	Carbon Black (C)	1333-86-4		0.014	mg
			Supplier	Ortho-Cresol Novolac Resin	29690-82-2		0.112	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.063	mg
Plating	0.06	mg	Supplier	Tin (Sn)	7440-31-5		0.06	mg
Wire Bond - Au	0.03	mg	Supplier	Gold (Au)	7440-57-5		0.03	mg